

WHAT IS CLAIMED IS:

1. An insulating sheet comprising:
 - a buffer layer having buffering attributes;
 - an adhesive layer that is not adhesive at normal ambient temperature but exhibits adhesiveness when heated; and
 - an insulating resin film, wherein the buffer layer and the resin film are attached together by the adhesive layer.
2. The insulating sheet according to claim 1, wherein the adhesive layer is formed of resin that does not contain a silicone component.
3. The insulating sheet according to claim 1, wherein the resin film is formed from polyethylene terephthalate.
4. The insulating sheet according to claim 1, wherein the buffer layer is formed of urethane foam.
5. A hard disk device comprising:
 - a case for housing a hard disk;
 - a printed wiring board provided with a circuit for controlling the hard disk; and
 - an insulating sheet interposed between the printed wiring board and the case, wherein the insulating sheet comprises
 - a buffer layer having buffering attributes,
 - an adhesive layer that is not adhesive at normal ambient temperature but exhibits adhesiveness when heated, and
 - an insulating resin film, wherein the buffer layer and the resin film layer are attached together by the adhesive layer.
6. The hard disk device according to claim 5, wherein the adhesive layer is formed of resin that does not contain a silicone component.

7. The hard disk device according to claim 5, wherein the resin film is formed from polyethylene terephthalate.

8. The hard disk device according to claim 5, wherein the buffer layer is formed of urethane foam.

9. A method of manufacturing an insulating sheet, comprising the steps of: bringing a sheet into contact with a buffer layer having buffering attributes, wherein the sheet comprises an insulating resin film and an adhesive layer attached to the insulating resin film, wherein the adhesive layer has a property of exhibiting adhesiveness when heated; and heating the adhesive layer while pressing against the buffer layer; thereby attaching the resin film to the buffer layer with the adhesive layer.